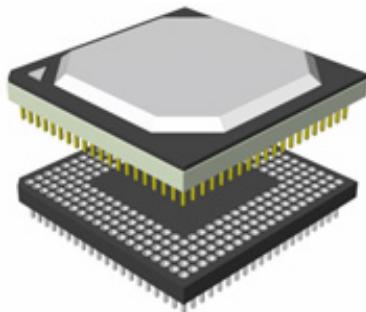


## Mini Grid Socket

The E-tec BGA Adapter System comprises two elements, the BGA solder adapter (see Part I) and the Mini Grid Socket shown on this page. The Mini Grid Socket is soldered to the target board and is designed to accept the BGA Solder Adapter (where the chip is soldered to the adapter board). As an alternative, this Mini Grid Socket is also designed to accept the „true“ through hole BGA Sockets (where the chips can be socketed without soldering).

E-tec offers any pin-out, configuration and grid size.

Special terminal designs are possible on request.



Solder Adapter  
with BGA Chip

Mini Grid Socket

		<b>male Pin Type 774</b>			<b>SMT Standard Type</b>	<b>SMT floating Type (only 1,27mm pitch)</b>			<b>Soldertail Terminal Type 117</b>	<b>Soldertail Terminal Type 172</b>			<b>Soldertail Terminal Type 174</b>	<b>male pin Type 774</b>
<b>Terminal styles</b>														

### Specifications

Terminal Type	Material	Plating	Socket & Adapter	Others
774	CuZn	Au over Ni over Cu	Material FR 4 glass Epoxy UL 94V-0	Operating Temperature -55°C to +125°C ; 260°C for 60 sec.
117, 119, 120, 167	Terminal : CuZn Contact clip : BeCu	Sn over Ni over Cu Au over Ni over Cu		

### How to order

Mini Grid Socket

MGS xxxx - E xxx - xx X 95 xx

Nbr of contacts/balls as per device	Terminal styles <small>Please refer to the drawings shown above.</small>	Grid size <small>will be given by the factory after receipt of the chip datasheet.</small>	Config Code <small>If Mini-Grid Sockets for PGA requested pls. refer to page 45</small>	Plating <small>95 = tin/gold (tin leadfree)</small>	Pitch of Grid Array <small>08 = 0.80mm 10 = 1.00mm 12 = 1.27mm 15 = 1.50mm 20 = 2.00mm others on request</small>
				for male pin -774 plating gold only = 55	